PCN Number:	20210920000.1	**PCN Date:**	September 20, 2021
Title:	Qualification of additional Fab site (UMC-F12) and additional Assembly site (Clark) for select LBC9 devices		
Customer Contact:	PCN Manager	**Dept:**	Quality Services
Proposed 1st Ship Date:	Dec 18, 2021	**Estimated Sample Availability:**	Date provided at sample request.

Change Type:

☒	Assembly Site	☐	Assembly Process	☒	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☐	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☒	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process
		☐	Part number change		

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of an additional fab (UMC-F12) and assembly site (Clark) for the selected devices listed in the "Product Affected" section.

Current Fab Site			New Fab Site		
Current Fab Site	**Process**	**Wafer Diameter**	**New Fab Site**	**Process**	**Wafer Diameter**
RFAB	LBC9	300 mm	UMC-F12	LBC9	300 mm

There are no construction differences between the 2 sites

Qual details are provided in the Qual Data Section.

Reason for Change:

Continuity of supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings:

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
RFAB	RFB	USA	Richardson
UMC-F12	**F12**	**TWN**	**Tainan**

Assembly Site Information:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
CDAT	CDA	CHN	Chengdu
Clark	**QAB**	**PHL**	**Angeles City, Pampanga**

Sample product shipping label (not actual product label)

G4

MADE IN: Malaysia
2DC: 2Q:

MSL 2 /260C/1 YEAR	SEAL DT
MSL 1 /235C/UNLIM	03/29/04

OPT:
ITEM: 39
LBL: 5A (L)T0:1750

(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T)LOT: 3959047MLA
(4W) TKY(1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO:USA
(22L) ASO: MLA (23L) ACO: MYS

Product Affected:

BQ25975YFFR	BQ25975YFFT	BQ25980YFFR	BQ25980YFFT

TI Information
Selective Disclosure

Qualification Report

Approve Date 13-Sep-2021

Qualification Results
Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: BQ25980YFF	Qual Device: BQ25975YFF	QBS Product Reference: BQ25980YFFR	QBS Product Reference: BQ25980YFFR	QBS Package Reference: CD3232A0YFFR...	QBS Package Reference: CD3232A1YFFR
-	Bump-Shear	(Per A-T site spec)	-	-	3/150/0	-	1/50/0	-
-	Manufacturability TQ - Testability)	(per mfg. Site specification)	1/Pass	1/Pass	-	-	-	-
-	Pb Surface Mount Solderability	Post 8 Hrs/Steam	-	-	3/66/0	-	-	-
CDM	ESD - CDM	750 V	1/3/0	-	-			
CDM	ESD - CDM	1000 V	-	-	-	1/3/0	-	-
CDM	ESD - CDM	1500 V	-	-	1/3/0	-	-	-
HAST	Biased HAST, 130C/85%RH	96 hours	3/231/0	-	3/231/0	-	2/160/0	-
HBM	ESD - HBM	4000 V	1/3/0	-	1/3/0	1/3/0	-	-
HTOL	Life Test, 125C	1000 hours	1/77/0	-	1/77/0	-	1/77/0	2/144/0
HTSL	High Temp Storage Bake 150C	1000 hours	3/231/0	-	-	-	-	-
HTSL	High Temp Storage Bake 170C	420 hours	-	-	3/231/0	-	1/77/0	1/77/0
LU	Latch-up	(Per JESD78, Class I)	1/6/0	-	1/6/0	1/6/0	-	-
LU	Latch-up	(Per JESD78, Class II)	1/6/0	-	1/6/0	1/6/0	-	-
MQ	Manufacturability (Bump)	(per mfg. Site specification)	1/Pass	-	-	-	-	-
PD	Physical Dimensions	(per mechanical drawing)	-	-	3/15/0	-	1/5/0	1/20/0
SBS	Bump-shear	(Per A-T site spec)	-	-	-	-	1/50/0	-
SD	Pb Free Surface Mount Solderability	Post 8 Hrs/Steam	-	-	3/66/0	-	1/22/0	1/22/0

Type	Test Name / Condition	Duration	Qual Device: BQ25980YFF	Qual Device: BQ25975YFF	QBS Product Reference: BQ25980YFFR	QBS Product Reference: BQ25980YFFR	QBS Package Reference: CD3232A0YFFR...	QBS Package Reference: CD3232A1YFFR
TC	Temperature Cycle, -55/125C	700 cycles	3/231/0	-	3/231/0	-	2/160/0	-
UHAST	Unbiased HAST 130C/85%RH	96 hours	3/231/0	-	3/231/0	-	-	-

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

- QBS: Qual By Similarity
- Qual Device BQ25975YFF is qualified at LEVEL1-260C
- Qual Device BQ25980YFF is qualified at LEVEL1-260C

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

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